



## Product Change Notification / RMES-06ZXIX068

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### Date:

24-Nov-2023

### Product Category:

FPGA Configuration Memory

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4241.001 Cancellation Notice: For the qualification of G700LS molding compound for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC package (300 mils) at ANAP assembly site.

### Affected CPNs:

[RMES-06ZXIX068\\_Affected\\_CPN\\_11242023.pdf](#)

[RMES-06ZXIX068\\_Affected\\_CPN\\_11242023.csv](#)

### Notification Text:

**PCN Status:**Cancellation Notification

**Microchip Parts Affected:**This change would have affected AT17LV002-10SU catalog part number (CPN) available in 20L SOIC package (300 mils) at ANAP assembly site.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**This qualification was originally performed to qualify G700LS molding compound for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC package (300 mils) at ANAP assembly site.

**Impacts to Data Sheet:**Not applicable.

**Change Impact:**Not applicable.

**Reason for Change**Microchip has decided to not qualify G700LS molding compound for AT17LV002-10SU catalog part number (CPN) available in 20L SOIC package (300 mils) at ANAP assembly site.

**Change Implementation Status:**Not applicable

**Estimated Qualification Completion Date:**Not applicable

**Revision History:**December 06, 2021: Issued initial notification.  
November 24, 2023: Issued cancellation notice.

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

AT17LV002-10SU